



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS3050EJ		<b>Issued</b>		19. August 2018		
<b>MA#</b>		MA001469596						
<b>Package</b>		PG-TDSO-8-31		<b>Weight*</b>		67.45 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.461	2.17	2.17	21665	21665
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		141	
	non noble metal	zinc	7440-66-6	0.038	0.06		563	
	non noble metal	iron	7439-89-6	0.760	1.13		11264	
wire	non noble metal	copper	7440-50-8	30.851	45.74	46.94	457381	469349
	non noble metal	copper	7440-50-8	0.322	0.48	0.48	4779	4779
	encapsulation	organic material	carbon black	1333-86-4	0.096	0.14		1428
plastics	plastics	epoxy resin	-	3.757	5.57		55700	
		inorganic material	silicondioxide	60676-86-0	28.258	41.89	47.60	418941
leadfinish	non noble metal	tin	7440-31-5	0.497	0.74	0.74	7372	7372
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12228	12228
glue	plastics	epoxy resin	-	0.101	0.15		1494	
	noble metal	silver	7440-22-4	0.475	0.70	0.85	7044	8538
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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